

Title (en)

OPTICAL MODULE AND METHOD FOR MANUFACTURING SAME

Title (de)

OPTISCHES MODUL UND VERFAHREN ZU SEINER HERSTELLUNG

Title (fr)

MODULE OPTIQUE ET PROCEDE DE FABRICATION DE CELUI-CI

Publication

**EP 1564573 A4 20070606 (EN)**

Application

**EP 03810591 A 20031104**

Priority

- JP 0314076 W 20031104
- JP 2002325604 A 20021108

Abstract (en)

[origin: EP1564573A1] The present invention relates to an optical module which can be produced by an easy process and at low cost and a method for fabricating the optical module. An optical module 100 includes a die pad 101, a plurality of leads 102, and a first platform 110 and a second platform 120 disposed on the die pad 101. At least an optical fiber 113 is fixed to a first platform body 111 and at least a light emitter 124 adapted for generating optical signals to be transmitted through the optical fiber 113 is mounted on a second platform body 121. <IMAGE>

IPC 1-7

**G02B 6/42**; **H01S 5/022**

IPC 8 full level

**G02B 6/42** (2006.01); **H01S 5/0232** (2021.01); **H01S 5/0683** (2006.01)

CPC (source: EP US)

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Citation (search report)

- [A] US 2002080457 A1 20020627 - NAKANISHI HIROMI [JP], et al
- See references of WO 2004042444A1

Designated contracting state (EPC)

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DOCDB simple family (publication)

**EP 1564573 A1 20050817**; **EP 1564573 A4 20070606**; CN 1720473 A 20060111; JP WO2004042444 A1 20060309; TW 200412737 A 20040716; TW I227970 B 20050211; US 2006239621 A1 20061026; WO 2004042444 A1 20040521

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